In the Claims:

This listing of claims will replace all prior versions and listings of claims in the application:

1. (Currently Amended) An optical sensor circuit assembly, comprising:

an optically transmissive substrate, an electrical circuit on a first surface of the optically transmissive substrate, the electrical circuit including electrically conductive leads;

an integrated circuit including an optical imaging element and electrically conductive pads on a face of the integrated circuit; and

a lens mount supporting a lens coupled to a second surface of the optically transmissive substrate opposite the first surface of the optically transmissive substrate;

the optical imaging element electrically coupled to the electrical circuit on the substrate by an electrical connection between the electrically conductive pads on the face of the integrated circuit and the electrically conductive leads of the electrical circuit on the substrate.

2. (Previously Presented) The optical sensor circuit assembly of claim 1, wherein the optically transmissive substrate includes filter material, said filter material embedded in said substrate.

3. (Previously Presented) The optical sensor circuit assembly of claim 1, wherein the optically transmissive substrate includes filter material, said filter material dispersed in said substrate.

4. (Previously Presented) The optical sensor circuit assembly of claim 1, wherein the optically transmissive substrate includes filter material, said filter material comprising a thin film layer on the substrate.

5. (Original) The optical sensor circuit assembly of claim 4, wherein said thin film layer further comprises material having antireflective properties.

6. (Canceled).

7. (Canceled).

8. (Currently Amended) The optical sensor circuit assembly of claim 1, wherein the optical imaging element is electrically coupled to the ~~integrated~~ electrical circuit by electrically conductive bumps disposed between the leads and the pads.

9. (Original) The optical sensor circuit assembly of claim 1, further comprising at least one optical element positioned to direct electromagnetic radiation through said substrate and filter material and to said optical imaging element.

10. (Canceled).

11.-19. (Canceled).

20. (New) The optical sensor circuit assembly of claim 1, further comprising an optically transmissive medium disposed between the integrated circuit and the optically transmissive substrate.